

REMARKS

Claims 15-21 are pending. By this Amendment, claim 17 is amended.

Applicant gratefully acknowledges that the Office Action indicates that claims 15, 16 and 18-21 are allowed.

The attached Appendix includes a marked-up copy of the rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).

Reconsideration based on the following remarks is respectfully requested.

I. The Claims Satisfy the Requirements fo 35 U.S.C. §112, First Paragraph

The Office Action rejects claim 17 under 35 U.S.C. §112, first paragraph. Claim 17 is amended to obviate this rejection. Specifically, claim 17 is amended to recite that the indented portion of the substrate is a surface of a thinner portion of the substrate. Support for this feature is found in Fig. 12 of the present application, wherein the substrate 50 has a thinner portion 56 at the corner portion, and a surface of the thinner portion 56 is indented further inward than an portion of the resin 52. Further support of this feature is found in the specification at page 26, lines 2-5.

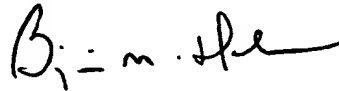
Withdrawal of the rejection under 35 U.S.C. §112, first paragraph is respectfully respected.

II. Conclusion

In view of the foregoing, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt allowance are earnestly solicited.

Should the Examiner believe anything further is desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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TECHNOLOGY CENTER 2800

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JAO:BMH/gpn

Attachment:
Appendix

Date: October 23, 2002

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>

APPENDIX

Changes to Claims:

17. (Twice Amended) The semiconductor device as defined in claim 15,
wherein the indented portion of the substrate ~~is~~ has a thinner portion at the
~~corner portion, and a surface of the~~ a thinner portion of the substrate is indented further
~~inward than the portion of the resin.~~